



HS1DDF

1.0A SURFACE MOUNT HYPER-FAST RECTIFIER

Product Summary (@T_A = +25°C)

V _{RRM} (V)	I _O (A)	V _F (MAX) (V)	I _{R(MAX)} (μA)
200	1	1.1	5

Features and Benefits

- Low Profile, Small Form Factor Package
- Low Leakage Current
- Glass Passivated for High Reliability
- Hyper-Fast Recovery Times for High Efficiency
- Low Forward Voltage, Low Power Loss
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Description and Applications

The HS1DDF is a rectifier packaged in the D-FLAT package and is suited as boost diode in power factor correction circuitry. For use in secondary rectification and freewheeling for superfast switching speed AC-DC and DC-DC converters in high temperature conditions for consumer applications.

- **DC-DC Converters**
- AC-DC Adaptors/Chargers
- Inverters

Mechanical Data

- Case: D-FLAT
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Polarity: Cathode Band
- Weight: 0.0354 grams (Approximate)



Top View



Schematic View

Ordering Information (Note 4)

Part Number	Qualification	Case	Packaging
HS1DDF-13	Commercial	D-FLAT	10,000/Tape & Reel

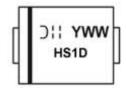
D-FLAT

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

D-FLAT



HS1D = Product Type Marking Code = Manufacturers' Code Marking YWW = Date Code Marking Y = Last Digit of Year (ex: 7 for 2017) WW = Week Code (01 to 53)



Maximum Ratings and Electrical Characteristics (@T_A = +25°C unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	200	٧
Average Rectified Output Current @T _C = +88°C (Note 5)	lo	1.0	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	40	Α

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Terminal (Note 6)	$R_{ heta JT}$	60	°C/W
Typical Thermal Resistance Junction to Ambient (Note 6)	R _{0JA}	92	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

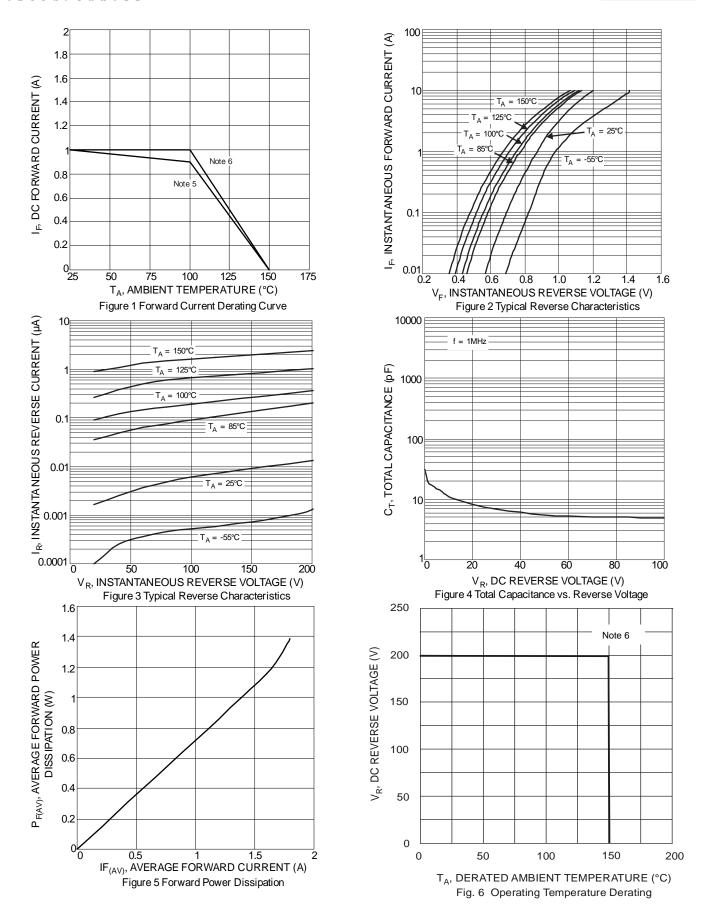
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	$V_{(BR)R}$	200	_	1	V	$I_R = 10\mu A$
Forward Voltage Drop	V _F	_	0.87 0.91 0.71	1.1 1.2 —	V	I _F = 1A, T _J = +25°C I _F = 1.5A, T _J = +25°C I _F = 1A, T _J = +125°C
Leakage Current (Note 7)	I _R		0.02 1.2	5 100	μΑ	$V_R = 200V, T_J = +25^{\circ}C$ $V_R = 200V, T_J = +125^{\circ}C$
Reverse Recovery Time	t _{RR}	_	12	15	ns	$I_F = 0.5A$, $I_R = 1.0A$, $I_{RR} = 0.25A$
Total Capacitance	C _T	_	16	_	pF	$V_R = 4.0V_{DC}$, $f = 1MHz$

Notes:

- 5. Device mounted on FR-4 substrate, 1" x 1", 2oz, single-sided, PC boards with 0.1" x 0.15" copper pad.
 6. Device mounted on FR-4 substrate, 0.4" x 0.5", 2oz, single-sided, PC boards with 0.2" x 0.25" copper pad.
 7. Short duration pulse test used to minimize self-heating effect.







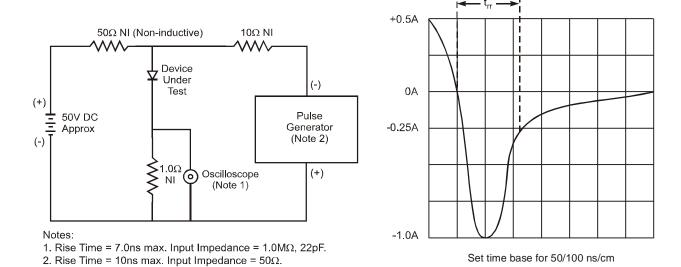
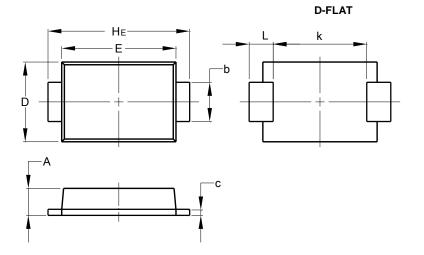


Fig. 7 Reverse Recovery Time Characteristic and Test Circuit



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

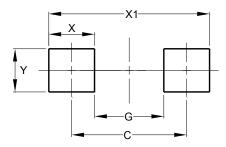


	D-FLAT				
Dim	Min	Max			
Α	0.90	1.10			
b	1.25	1.65			
С	0.10	0.40			
D	2.25	2.95			
Е	3.95	4.60			
k	2.80	-			
HE	5.00	5.60			
Ĺ	0.50	1.30			
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

D-FLAT



Dimensions	Value (in mm)
С	4.65
G	2.80
Х	1.85
X1	6.50
Y	1.70



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